

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Canceled).
2. (Currently Amended) The method of manufacturing a semiconductor device as defined in ~~claim 1~~, claim 18,

wherein the interconnecting lines comprise connecting portions electrically connecting with the bumps, and

wherein in the step of electrical connection, the base substrate is melted, so that connections of the bumps and the connecting portions are sealed with the melted material of the base substrate.
3. (Currently Amended) The method of manufacturing a semiconductor device as defined in ~~claim 1~~, claim 18,

wherein the melted material of the base substrate is adhered closely to a surface of the semiconductor chip.
4. (Canceled).
5. (Currently Amended) The method of manufacturing a semiconductor device as defined in ~~claim 1~~, claim 18,

wherein a thermoplastic resin is used as the base substrate.
6. (Canceled).
7. (Currently Amended) The method of manufacturing a semiconductor device as defined in ~~claim 1~~, claim 18, further comprising:

mounting another semiconductor chip on the wiring substrate.
8. (Currently Amended) A semiconductor device manufactured by the manufacturing method as defined in ~~claim 1~~, claim 18.

9.-17. (Canceled)

18. (Previously Presented) A method of manufacturing a semiconductor device including a step of mounting a semiconductor chip on a wiring substrate having a base substrate on which are formed interconnecting lines, the method comprising:

mounting the semiconductor chip on the base substrate so that a surface of the base substrate opposite to the surface on which the interconnecting lines are formed is in contact with bumps formed on the semiconductor chip; and

electrically connecting the bumps to the interconnecting lines by heating at least the bumps and pressing the semiconductor chip toward the base substrate so that the base substrate is melted and the bumps are pushed into the base substrate.